

Wafering & Abrasive Blades



ISOMET™ Diamond Wafering Blades

- Proprietary high tech family of blades developed specifically to provide precise sections of metallographic specimens
- These thin blades (< 1mm) are ideal for sectioning small specimen
- Choose from 27 different blades, including 6 different diameters and high or low concentrations



ISOCUT™ Wafering Blades

- Specifically developed to section ferrous materials such as iron-, cobalt-, lead-, and nickel-based alloys & superalloys
- These thin blades (< 1mm) ensure precise sections
- The special formulation of cubic boron nitride (CBN) particles will significantly reduce the sectioning time of ferrous materials when compared to standard diamond wafering blades



BUEHLER Diamond Cut-Off Blades

- Available in Resin Bond, RIMLOCK* and Continuous Rim
- Resin Bonded Diamond Blades are specifically developed for precision sectioning of carbide materials
- RIMLOCK Diamond Blades are ideal for quick and rough sectioning of petrographic materials
- Continuous Rim Diamond Blades are formulated for precision sectioning of petrographic materials



BUEHLER DELTA™ & METABRASE™ Cut-Off Wheels

- Choose from a large selection (57 different wheels) of application specific blades
- The silicon carbide wheels are formulated for non-ferrous and non-metallic materials
- The aluminum oxide wheels are designed for ferrous materials
- Coarse grits will cut heavier sections faster and cooler
- Fine grits produce better surfaces and less burning on delicate pieces
- Soft wheels break down faster exposing new cutting surfaces more rapidly - preferred for hard materials
- Hard wheels break down slower, wear longer and are recommended for softer materials



ACU-THIN™ Abrasive Cut-Off Blades

- The blades range in thickness from 0.019" (0.480mm) to 0.032" (0.813mm) depending on diameter
- Formulated for fast sectioning with minimum kerf loss
- Provide for cool cutting action
- Minimize the structural damage to the specimen